

SURFACE-MOUNT MULTI-LAYER CHIP BEADS

FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20% impedance tolerance

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products

ELECTRICAL CHARACTERISTICS:

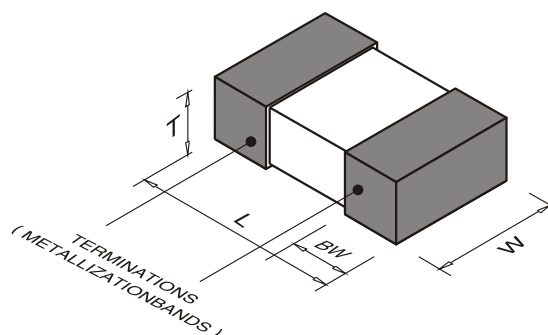
Part Number	IMPEDANCE Ω AT 100 MHz	DCR (Ω) Max	IDC Max mA	Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
D LCBB070-0.60A	7	0.20	600	D LCBC700-0.40A	70	0.30	400
D LCBB110-0.60A	11	0.20	600	D LCBC800-0.30A	80	0.30	300
D LCBB190-0.60A	19	0.20	600	D LCBC101-0.30A	100	0.30	300
D LCBB260-0.40A	26	0.20	400	D LCBC121-0.30A	120	0.30	300
D LCBB310-0.40A	31	0.20	400	D LCBC151-0.30A	150	0.30	300
D LCBB360-0.40A	36	0.20	400	D LCBC181-0.30A	180	0.35	300
D LCBB600-0.40A	60	0.25	400	D LCBC221-0.30A	220	0.30	300
D LCBB700-0.40A	70	0.25	400	D LCBC301-0.30A	300	0.30	300
D LCBB800-0.40A	80	0.25	400	D LCBC501-0.20A	500	0.30	200
D LCBB101-0.40A	100	0.25	400	D LCBC601-0.20A	600	0.30	200
D LCBB121-0.30A	120	0.25	300	D LCBC801-0.20A	800	0.30	200
D LCBB151-0.30A	150	0.25	300	D LCBC102-0.20A	1000	0.30	200
D LCBB181-0.30A	180	0.25	300	D LCBC122-0.10A	1200	0.50	100
D LCBB221-0.30A	220	0.25	300	D LCBC152-0.10A	1500	0.60	100
D LCBB301-0.30A	300	0.25	300	D LCBC202-0.10A	2000	0.60	100
D LCBB501-0.20A	500	0.35	200	D LCBC252-0.10A	2500	0.80	100
D LCBB601-0.20A	600	0.40	200	D LCBC302-0.08A	3000	1.00	80
D LCBB801-0.15A	800	0.40	150				
D LCBB102-0.10A	1000	0.45	100				
D LCBB122-0.10A	1200	0.06	100				
D LCBB152-0.10A	1500	0.80	100				
D LCBB202-0.05A	2000	0.90	50				
D LCBB222-0.05A	2200	1.00	50				
D LCBB252-0.05A	2500	1.20	50				
D LCBB302-0.05A	3000	1.40	50				
D LCBC190-0.50A	19	0.20	500				
D LCBC260-0.50A	26	0.20	500				
D LCBC310-0.50A	31	0.30	500				
D LCBC600-0.40A	60	0.30	400				

Note: 1. K = $\pm 10\%$, M = $\pm 20\%$

TECHNICAL INFORMATION PHYSICAL CHARACTERISTICS

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
Preheat: @ 260°C $\pm 5^\circ\text{C}$ for 60 seconds
Flux: Rosin, Dip for 10 seconds ± 1 second
- Thermal Shock: Impedance shall be within $\pm 20\%$ of initial value when temperature is -25°C and $+85^\circ\text{C}$ for 30 minutes for each 50 cycles
- Operating Temperature: -25°C to $+85^\circ\text{C}$
- Storage Temperature: -25°C to $+85^\circ\text{C}$

(Refer to Size Chart Page 4)



Note: All specifications subject to change without notice.